

Substitute form 1449A/PTO

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

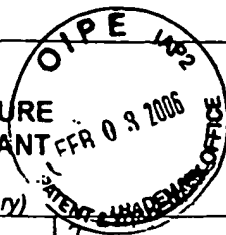
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Sheet

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of

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Complete if Known

Application Number	10/790,967
Filing Date	March 2, 2004
First Named Inventor	Glenn A. Rinne
Group Art Unit	1725
Examiner Name	Michael Aboagye
Attorney Docket Number	9180-10CT

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Examiner Initials*	Cite No.	U.S. Patent Document		Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY
		Number	Kind Code (if known)		
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Examiner Signature

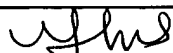
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INFORMATION DISCLOSURE STATEMENT BY APPLICANT (use as many sheets as necessary)			Application Number	10/790,967	
			Filing Date	March 2, 2004	
			First Named Inventor	Glenn A. Rinne	
			Group Art Unit	1725	
			Examiner Name	Michael Aboagye	
Sheet	2	of	7	Attorney Docket Number	9180-10CT

AM	49.	US-4,449,580	Reisman et al;	05/1984
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Examiner Signature		Date Considered	04/21/2006
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		Group Art Unit	1725
		Examiner Name	Michael Aboagye
(use as many sheets as necessary)		Attorney Docket Number	9180-10CT
Sheet	3	of	7

AM	102.	US-5,251,806	Agarwala et al.	10/12/1993
	103.	US-5,289,925	Newmark	03/1994
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AM	154.	US-6,027,957	Merritt et al.	02/2000

Examiner Signature	<i>[Signature]</i>	Date Considered	04/21/2008
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			Group Art Unit	1725
			Examiner Name	Michael Aboagye
(use as many sheets as necessary)			Attorney Docket Number	9180-10CT
Sheet	4	of	7	

AM	155.	US-6,083,773		Lake	07/04/2000
	156.	US-6,117,299		Rinne et al.	09/12/00
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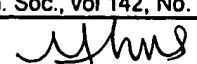
FOREIGN PATENT DOCUMENTS						
Examiner Initials*	Cite No.	Foreign Patent Document			Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY
		Office	Number	Kind Code (if known)		
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Examiner Name				Michael Aboagye		
Sheet	5	of	7	Attorney Docket Number		9180-10CT


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	202.	EP	1 146 552		Agere Systems Guardian Corporation	10/17/2001	
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	215.	JP	63-222445		Japan	09/1988	Abstract
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	227.	JP	2000349111		Fujitsu, Ltd.	12-15-2000	Abstract
	228.	JP	2002203868		Toshiba Corp	07-19-2002	Abstract
	229.	WO	02/03461		Intel Corporation	01/10/2002	
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AM	235.	WO	93/02831		PCT	02/1993	

OTHER NON PATENT LITERATURE DOCUMENTS				
Examiner Initials*	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published	T	
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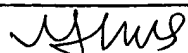
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	245.	Ezawa et al; <i>Pb-Free Bumping by Alloying Electroplated Metal Stacks</i> ; 2003 Electronic Components and Technology Conference; pp 664-667.	
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	247.	Greer "An Extended Eutectec Solder bump for FCOB" 1996 <i>Electronic Componets and Technology Conference</i> pp. 546-551 (1996)	
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Examiner Signature		Date Considered	04/21/2006
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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

Substitute form 1449A/PTO		Complete if Known	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (use as many sheets as necessary)		Application Number	10/790,967
		Filing Date	March 2, 2004
		First Named Inventor	Glenn A. Rinne
		Group Art Unit	1725
		Examiner Name	Michael Aboagye
Sheet	7	of	7
		Attorney Docket Number	9180-10CT

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